

## 1. Scope

The present specifications shall apply to FMXK-2206S.

## 2. Outline

High Frequency Rectification

Type	Silicon Diode
Structure	Resin Molded
Applications	High Frequency Rectification,etc

## 3. Flammability

UL94V-0(Equivalent)

*Not Recommended for New Designs*

## 4. Absolute maximum ratings

No.	Item	Symbol	Unit	Rating	Conditions
1	Transient Peak Reverse Voltage	$V_{RSM}$	V	600	
2	Peak Reverse Voltage	$V_{RM}$	V	600	
3	Average Forward Current	$I_{F(AV)}$	A	20	Refer to Derating curve of 7
4	Peak Surge Forward Current	$I_{FSM}$	A	100	10msec. Half sinewave, one shot
5	$I^2t$ Limiting Value	$I^2t$	$A^2s$	50	$1msec \leq t \leq 10msec$
6	Junction Temperature	$T_j$	$^{\circ}C$	-40~+150	
7	Storage Temperature	$T_{stg}$	$^{\circ}C$	-40~+150	

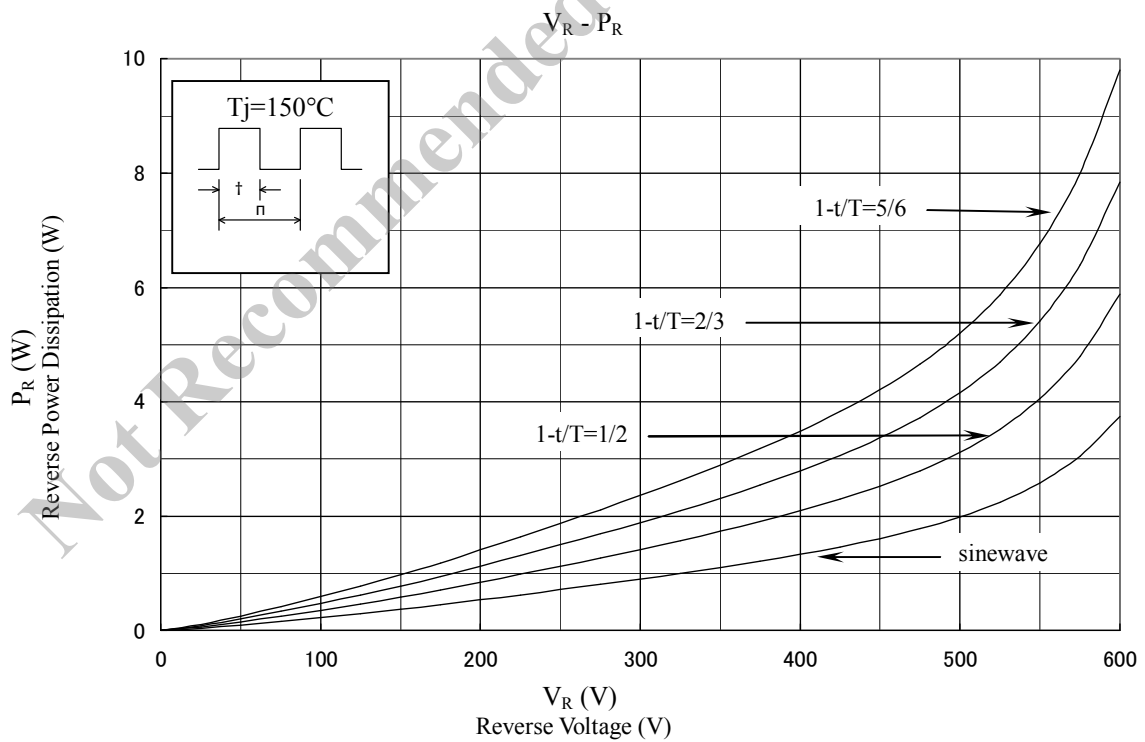
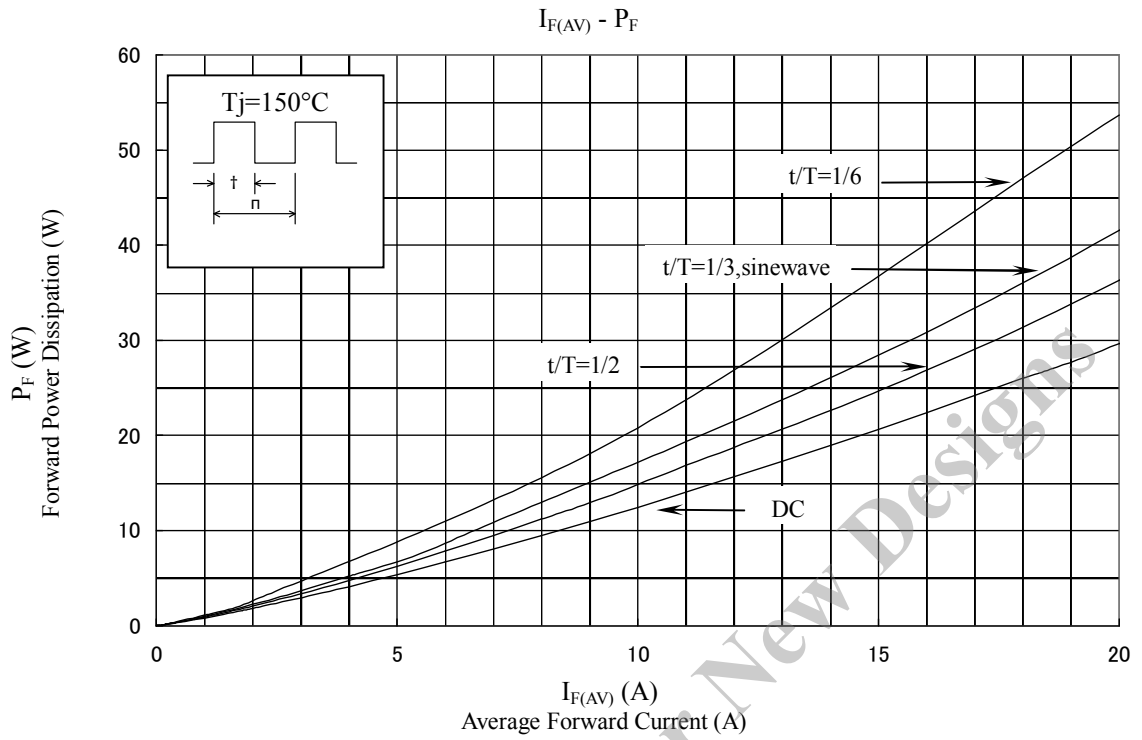
No.1,2,4&5 show ratings per one chip.

## 5. Electrical characteristics

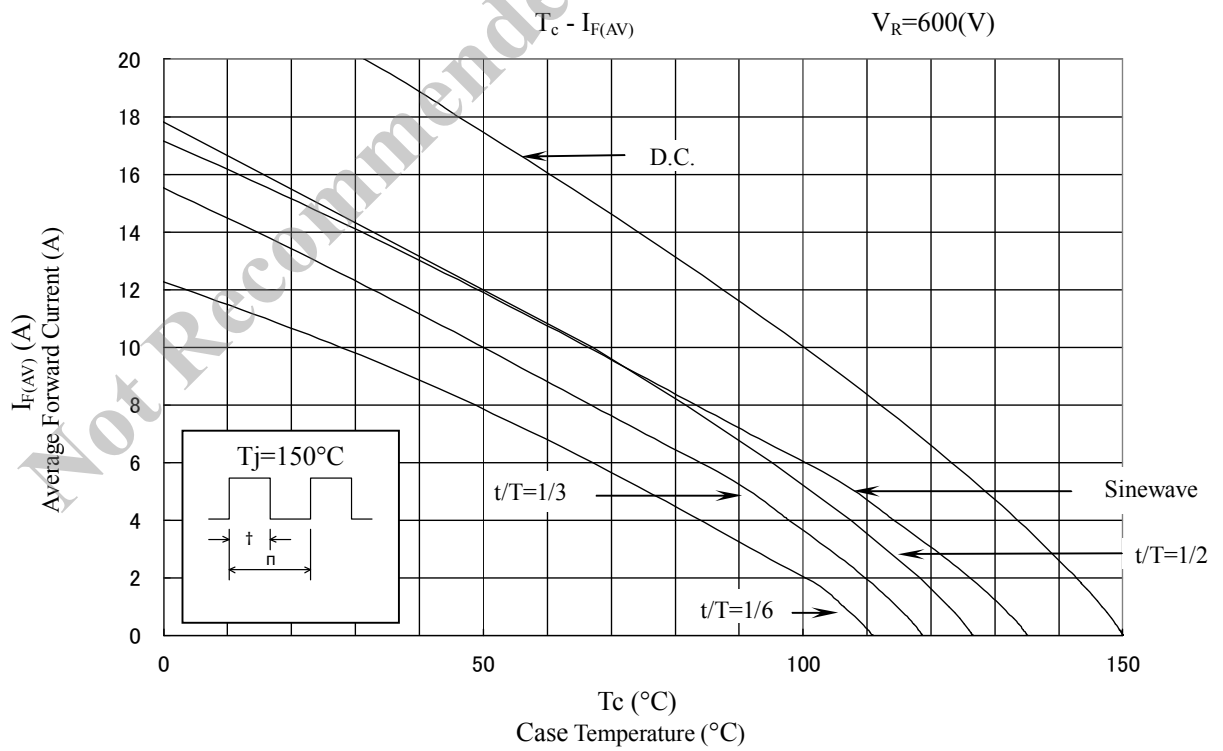
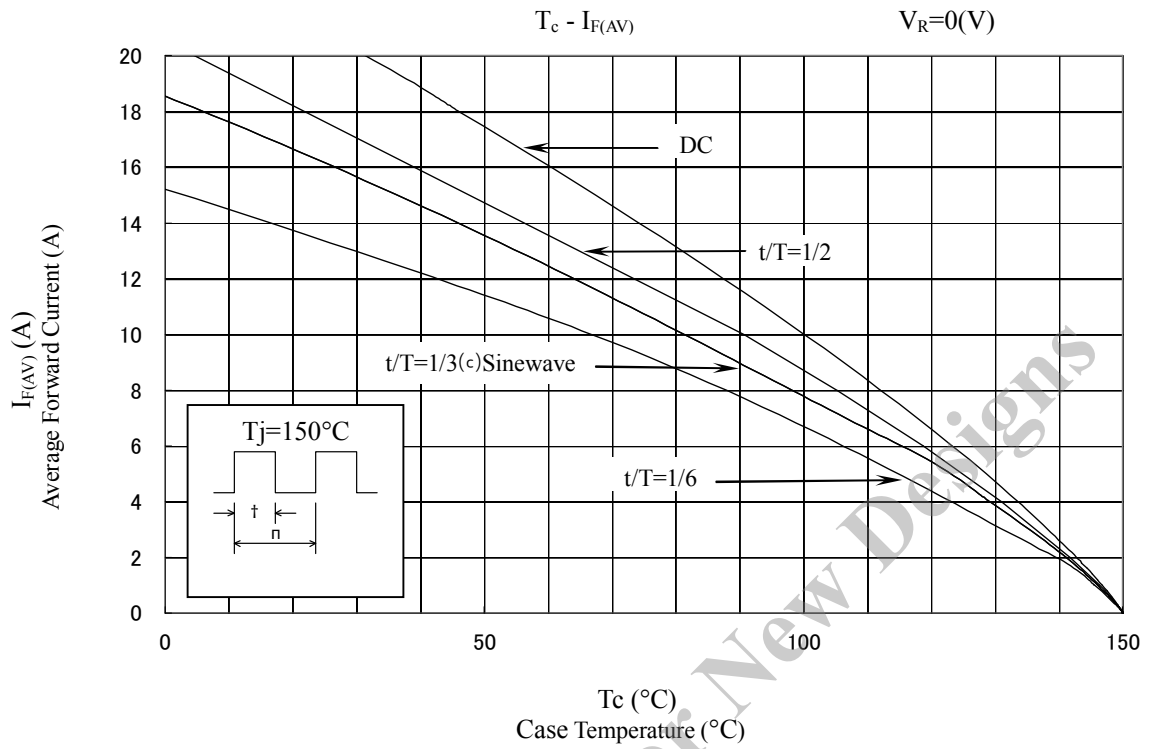
No.	Item	Symbol	Unit	Value	Conditions
1	Forward Voltage Drop	$V_F$	V	1.75 max.	$I_F=10A$
2	Reverse Leakage Current	$I_R$	$\mu A$	100 $\phi$ max.	$V_R=V_{RM}$
3	Reverse Leakage Current Under High Temperature	$H^n I_R$	mA	10 $\phi$ max.	$V_R=V_{RM}, T_j=150^{\circ}C$
4	Reverse Recovery Time	$t_{rr}$	ns	$\phi$ 27 $\phi$ max	$I_F=I_{RP}=500mA$ 75% Recovery point, $T_j=25^{\circ}C$
5	Thermal Resistance	$R_{th(j-c)}$	$^{\circ}C/W$	$\phi$ $\phi$ 4 $\phi$ max.	Between Junction and case

No.1,2,3&4 show characteristics per one chip.

6. Characteristics

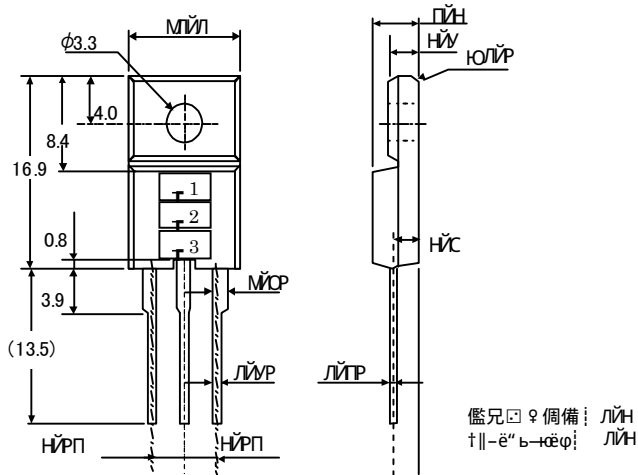


7. Derating



8. Package information

8-1 Package type, physical dimensions and material



Dimensions in 眩

8-2 Appearance

The body shall be clean and shall not bear any stain, rust or flaw.

8-3 Marking

Type Name	Marking		
	*1φ Type Name	*2φ Polarity	*3φ Lot number
FMXK-2206S	XK2206		1st letter: Last digit of year 2nd letter: Monthφ From 1 to 9 for Jan. to Sep., O for Oct., N for Nov., D for Dec. 3rd & 4th letter: Day ex. 8618φ (Jun. 18, 2008)

Not Recommended for New Designs